

ProTemp Furnace SOP

Scope

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1.1 This SOP provides instructions to operate the ProTemp Atmospheric Furnaces.

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3 Reference Documents

3.1 External Documents

3.1.1 SMBB Lab User Guide

4 Equipment and/or Materials

- 4.1 ProTemp Oxidation Furnaces
- 4.2 Quartzware
- 4.3 Boat fork
- 4.4 Monitor wafers
 - 4.4.1 Phosphorous Doping: <100> P-Type bare silicon
 - 4.4.2 All Other Processes: <100> N-Type or P-Type bare silicon
- 4.5 Filler wafers

5 Safety

- 5.1 Follow all Nanofab safety procedures.
- 5.2 Ensure all Cooldown cycles are complete before handling any quartzware, wafers, or samples.

	00000	CAUTION	00000	
		All recipes include the necessary cool down time to ensure the quartzware, wafers, and samples are cool enough to be touched and handled.		
		Do not touch or handle quartzware, wafers, or samples unless the current run is COMPLETE.		
	00000	CAUTION	00000	
6	General Informati	on		

6.1 Ensure all samples are authorized to be loaded into a furnace.

!!! WARNING !!!

No photoresist, kapton tape, metals, glass, or other foreign material is allowed in any furnace.

Only quartz, silicon, silicon carbide, silicon dioxide, silicon nitride, and/or Polysilicon are allowed without <u>PRIOR</u> approval of lab staff.

!!! WARNING !!!

- 6.1.1 Only the following substrates or samples are allowed in the **Clean Ox** furnace:
 - Bare silicon wafers that have received NO prior processing
 - Wafers with an oxide that was thermally grown in the Clean Ox furnace
 - Wafers with LPCVD Undoped Polysilicon deposition
 - Wafers with LPCVD Nitride deposition
- 6.1.2 The following substrates or samples are allowed in the **Doped Ox** furnace:
 - All samples approved for processing in the Clean Ox furnace
 - Wafers that have been processed through PECVD Oxide deposition
 - Wafers that have been processed through PECVD Polysilicon deposition
 - Wafers that have been processed through PECVD Nitride deposition
 - Wafers that have been processed through LPCVD Doped Poly Deposition
 - Wafers that have been processed through LPCVD LTO Deposition
 - Wafers that have been processed through LPCVD PSG Deposition
 - Wafers that have been doped by any method
- 6.1.3 **For any substrates or samples not listed above**, contact Staff to determine the authorized furnace.
- 6.2 Ensure all samples are clean, dry, and particle-free.
- 6.3 Place quartzware on a quartz plate, silicon carbide cantilever paddle, or a cleanroom wiper.
 - 6.3.1 Do NOT directly place quartzware on stainless steel.
- 6.4 Do NOT touch boats or boat covers with your hands.
 - 6.4.1 Use the boat fork (see Figure 1, Boat Fork) to move boats and boat covers.
 - 6.4.1.1 Insert the tines of the fork into the pick-up tubing on the boat or boat cover.







- 6.5 Before touching a quartz baffle, put on a second pair of clean blue nitrile gloves.
- 6.6 Solid Source wafers that have been out of the furnace more than one (1) hour need a dehydration bake per section 9 Solid Source Instructions.

7 Pre-Clean

- 7.1 **For new, unused bare silicon wafers**, a Pre-Diffusion Clean prior to processing through any furnace cycle is recommended.
- 7.2 **For all other samples/substrates/wafers**, a Pre-Diffusion Clean prior to processing through any furnace cycle is **REQUIRED**.
- 7.3 Complete the Pre-Diffusion Clean in the Pre-Diffusion wet bench.
 - *NOTE:* The dedicated baths should be used for whole wafers, since the SC-1 bath includes a megasonic clean for improved particle removal. However, for partial wafers the specified mixtures may be used in smaller beakers/containers, if necessary.
- 7.4 Refer to TABLE 1, FURNACE PRE-CLEAN for the correct mixtures, temperatures, and times.
- 7.5 If the Organic Clean bath temperature is above 100°C and has not been used within the last 2 hours, add 100ml of Hydrogen Peroxide.
 - 7.5.1 Wait at least 5 minutes before using the bath.

7.6 Organic Clean Bath Preparation

- 7.6.1 **If using an alternate bath container,** ensure the container is compatible with temperatures up to 200°C (e.g., pyrex, quartz, teflon).
- 7.6.2 Add the necessary amount of Sulfuric Acid to an empty container.
- 7.6.3 Turn on the heater.
- 7.6.4 Wait for the heater to exceed 100°C.
- 7.6.5 Add the necessary amount of Hydrogen Peroxide.
- 7.6.6 Wait until the bath temperature has reached setpoint.
- 7.6.7 Wait at least 5 minutes before using the bath.

7.7 SC-1 Bath Preparation

- 7.7.1 **If using an alternate bath container**, ensure the container is compatible with temperatures up to 100°C (e.g., pyrex, quartz, teflon).
- 7.7.2 Add the necessary amount of Ultra Pure Water (UPW) to an empty container.
- 7.7.3 Add the necessary amount of Ammonium Hydroxide.
- 7.7.4 Turn on the heater.
- 7.7.5 Wait for the heater to exceed 65°C.
- 7.7.6 Add the necessary amount of Hydrogen Peroxide.
- 7.7.7 Wait until the bath temperature has reached setpoint.
- 7.7.8 Wait at least 5 minutes before using the bath.

7.8 Oxide Removal Bath Preparation

- 7.8.1 **If using an alternate bath container**, ensure the container is compatible with Hydrofluoric Acid (e.g., plastic, teflon).
- 7.8.2 Add the necessary amount of Ultra Pure Water (UPW) to an empty container.
- 7.8.3 Add the necessary amount of Hydrofluoric Acid.
- 7.8.4 Wait at least 5 minutes before using the bath.

7.9 SC-2 Bath Preparation

- 7.9.1 **If using an alternate bath container**, ensure the container is compatible with temperatures up to 100°C (e.g., pyrex, quartz, teflon).
- 7.9.2 Add the necessary amount of Ultra Pure Water (UPW) to an empty container.
- 7.9.3 Add the necessary amount of Hydrochloric Acid.
- 7.9.4 Turn on the heater.
- 7.9.5 Wait for the heater to exceed 65°C.
- 7.9.6 Add the necessary amount of Hydrogen Peroxide.
- 7.9.7 Wait until the bath temperature has reached setpoint.
- 7.9.8 Wait at least 5 minutes before using the bath.

	TABLE 1, FURNACE PRE-CLEAN							
Step	Description	Container Type	Ratio ¹	Chemical	Quantity (ml)	Temp (°C)	Time (mm:ss)	
1	Organic clean	Pvrex	5	Sulfuric Acid	2500	120	10:00	
_	(pirahna)	Quartz	1	Hvdrogen Peroxide, 30%	500			
J	()	Teflon						
2	Rinse			Ultra Pure Water (UPW)			5:00	
3	SC-1	Pyrex	5	Ultra Pure Water (UPW)	6250	75	10:00	
J	'	Quartz	1	Ammonium Hydroxide	1250			
J	'	Teflon	0.4	Hydrogen Peroxide	500			
4	Rinse			Ultra Pure Water (UPW)			5:00	
5	Oxide Removal	Plastic	50	Ultra Pure Water (UPW)	2000		01:00	
	'	Teflon	1	Hydrofluoric Acid, 49%	40			
6	Rinse			Ultra Pure Water (UPW)			5:00	
7	SC-2	Pyrex	6	Ultra Pure Water (UPW)	3900	75	10:00	
	'	Quartz	1	Hydrochloric Acid, 37%	650		1	
	'	Teflon	1	Hydrogen Peroxide	650		1	
8	Rinse			Ultra Pure Water (UPW)			5:00	
9	Spin-Rinse Dry		As programmed					
¹ Maint:	ain this ratio wher	using the al	ternate '	bath containers.				
² lf the (Organic clean batł	1 temperatur	e is grea	ter than 100°C and has been	unused for	more th	an 2	
hours,	add 100ml of Hyd	rogen Peroxi [,]	de prior	to use.				

LOG IN INFORMATION

Doped Ox

DOPEDOX

DOPEDOX

Log In

8 **Furnace Operating Procedures**

8.1 <u>Log On</u>

- From the ProTemp host computer, select the Tymplex program. 8.1.1
 - If necessary, open the Tymplex program. 8.1.1.1
- From the **Overview** screen, click the **Log In** button. 8.1.2
- 8.1.3 Type the Username and password (in CAPS) for the applicable furnace. (See TABLE 2, LOG IN INFORMATION.)
- From the **User Login ...** dialog box, click the **Log In** button. 8.1.4

	Uver View		4 Tube 4TC	ТА	BLE	2, Log In In
		NTEGRATED		Furnace	•	Clean Ox
	TymPlex™ Mult	ME SYSTEMS, INC. www.intyme.com ti-Tool Host Software. Version 3.05.0014		Usernar	ne	CLEANOX
	Computer Name: OWNER: User Data Location:	-PC; OS: Windows 7/Server 2008 R2, V6.1, 32 : C:\Users\Public\Documents\TymkonTools\	bits	Passwoi	rd	CLEANOX
C	Log In Disable Tool Tips Disable Hol Keys Configure TyuePro TyuePro TyueCot Alam Silence	Batasis Batasis Recipe <u>16 WEI 07, Poberci</u> Orde Z Segment <i>14</i> size 100 1983/00 Orde Time 82/Manuse Total Time 25/48/10 Configuration 80M/8722	Batus Batus Recipe 28: DOWN AND OUT Cycle 2 Segment 11: DOWN AND OUT Tenp: 34: Count Anno Cycle Time 6: 1 Minutes Telat Time 6: 80:028 Configuration: 80:640722	User Login Current Us Select Net Enter Pass	er is: w User: sword: ncel	"Default User CLEANOX Log Qut

8.2 Enable Coral

8.2.1 Enable the furnace in Coral.

8.3 Check Furnace Status

- Select the main tab for the desired furnace. 8.3.1
- 8.3.2 Select the Operate subtab.

8.3.3 **Review Current Status**

- NOTE: If the current recipe is "IDLE WITH COMPLETED SAMPLES ON BOAT", samples from the previous run have not been removed from the boat.
- If the current recipe is "IDLE WITH COMPLETED SAMPLES ON BOAT", do the 8.3.3.1 following:
 - 8.3.3.1.1 If there are no instructions from the previous user, contact that user before removing any samples and monitor wafers.
 - 8.3.3.1.2 If the instructions from the previous user are "Do Not Disturb", do not proceed.



8.3.3.1.3 If the instructions from the previous user authorize you to handle their samples, continue.



- 8.3.3.2 If there is a blue dot next to the **Step** button, the furnace is on Hold.
 - 8.3.3.2.1 Click the **Run** button.
 - 8.3.3.2.2 Wait for the current run to complete.
 - *NOTE:* The **Alarm Silence** button will be replaced by a
 - *yellow* ***** Complete ***** *button with a yellow dot.*
- 8.3.3.3 If there is a yellow dot next to the ***** Complete ***** button, the current recipe has completed.





- 8.3.3.3.1 Click the ***** Complete ***** button.
- 8.3.3.3.2 Click the **Reset** button.
- 8.3.3.4 **If the cantilever is in and there is a blue dot next to the Reset button**, download and run the "BOAT OUT" recipe per paragraphs 8.7 Download Recipe File through 8.9 Run Recipe.
- 8.3.3.5 If the cantilever is in and there is a yellow dot next to the ***** Complete ***** button, click the ***** Complete ***** button.
 - 8.3.3.5.1 Download and run the "BOAT OUT" recipe per paragraphs 8.7 Download Recipe File through 8.9 Run Recipe.
- 8.3.3.6 **If the cantilever is out**, the furnace is ready for use.
- 8.3.3.7 **If samples from another member are loaded on the boat AND he/she has authorized you to handle their samples**, follow their instructions to remove the samples.

8.4 Load Boat

8.4.1 Load Wafers

$\Lambda\Lambda$!!! WARNING !!!	$\Lambda \Lambda$				
\bigwedge	No photoresist, kapton tape, metals, glass, or other foreign material is allowed in the furnace.	\bigwedge				
	Only quartz, silicon, silicon carbide, silicon dioxide, silicon nitride, and/or					
	Polysilicon are allowed without <u>PRIOR</u> approval of lab staff.					
$\Lambda \Lambda$!!! WARNING !!!	$\Lambda \Lambda$				
8.4.1.1	Unless otherwise noted , load all wafers with the polished side toward of the furnace.	the door				
8.4.1.2	Load the wafers with the wafer flat up.					
8.4.1.3	Load one wafer per slot.					
8.4.1.4	Solid Source Doping					
	NOTE: Solid Source wafers that have been out of the furnace more than hour need a dehydration bake per section 9 Solid Source Instru	n one (1) ctions.				
	<i>NOTE: The solid source wafers should always have a filler or sample w</i> <i>the adjacent slots – even when stored.</i>	vafer in				
	8.4.1.4.1 Remove the necessary filler wafers (adjacent to the solid source v	wafers) and				

- place them in empty slots at either end of the boat.8.4.1.4.2 Load all sample and monitor wafers with the polished side (side to be
- 8.4.1.4.2 Load all sample and monitor wafers with the polished side (side to be doped) toward the solid source wafer.
- 8.4.1.4.3 Load a monitor wafer onto the boat in slot 14 (see Figure 2, Solid Source Doping Loading Diagram).



- *NOTE:* Monitor wafers for Phosphorous Doping are <100> P-Type bare silicon. Monitors wafers for Boron Doping are <100> N-Type bare silicon.
- 8.4.1.4.4 Load sample wafers in slots 9-13 and/or 15-18, starting at the center.

8.4.1.4.5 Load filler wafers in slots 4-7, 20-23, and all unused sample slots.



8.4.1.5 Oxidation/Anneal









8.5 Initialize Graph

- 8.5.1 Select the **Setup** subtab.
- 8.5.2 Ensure the Enable Datalog check box is checked.
- 8.5.3 Press the **Create New Datalog** File button.
- 8.5.4 At the **Creating new datalog file ...** box, click OK .





8.6 Change Oxidation Time

- 8.6.1 From the desktop, open the "Change OxTime" utility.
- 8.6.2 Enter/select your Coral ID.
- 8.6.3 Following the prompts, change the oxidation time, if needed.





8.7 Download Recipe File

- 8.7.1 To download a new recipe file, select the **Download** subtab.
- 8.7.2 Click the **Download File to Tymkon** button.
- 8.7.3 From the dialog box, locate and select the correct recipe file (see TABLE 3, RECIPE FILE LOCATION).
- 8.7.4 From the **Ready to Download** dialog box, click the **Begin Download** button.
- 8.7.5 Wait for the recipe to complete downloading. (Sections will change from red to black text.)

Download subtab



- Download File to Tymkon button

This text changes from red to black when download is complete.

	TABLE 3, RECIPE FILE LOCATION						
Furnace	Path	Recipe Type	Recipe File				
CleanOx	[MainPath]\CleanOx\CleanOx Recipes	Dry Oxidation	Clean DryOx Recipes.mdb				
		Wet Oxidation	Clean WetOx Recipes.mdb				
DopedOx	[MainPath]\DopedOx\DopedOx Recipes	Anneal	Doped Anneal Recipes.mdb				
		Boron Doping	Boron Solid Source Recipes.mdb				
		Dry Oxidation	Doped DryOx Recipes.mdb				
		Phosphorous Doping	Phos Solid Source Recipes.mdb				
		Wet Oxidation	Doped WetOx Recipes.mdb				
[MainPath	[MainPath] = C:\Users\Public\Documents\TymkonTools\UserData						

Select Recipe button



8.8 Select Recipe

- 8.8.1 Select the **Operate** subtab.
- 8.8.2 Click the **Select Recipe** v pull down box.
- 8.8.3 Select the desired recipe.
- 8.8.4 Activate the recipe by clicking the **Select Recipe # (recipe name)** button.

Select Recipe pull down box



8.9 Run Recipe

8.9.1 From the **Operate** subtab, click the Run button.





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8.10 Wait for Run Completion

- 8.10.1 Wait for the cooldown cycle to complete.
 - *NOTE:* The boat will be out, the current recipe will be "REMOVE SAMPLES" and the current cycle will be "REMOVE SAMPLES". If this recipe is not reset within a programmed amount of time, the system will start the "IDLE WITH COMPLETED SAMPLES ON BOAT" and the load will push back into the furnace.
- 8.10.2 Click the **Reset** button.
- 8.10.3 At the **Reset the current recipe ?** dialog box, click the **OK** button.

8.11 <u>Unload Boat</u>

8.11.1 Ensure the run has completed.

	00000	CAUTION	l i	00000
		All recipes include the necessa ensure the quartzware, wafers enough to be touched	ary cool down time to , and samples are cool and handled.	
		Do not touch or handle qua samples unless the current	rtzware, wafers, or run is COMPLETE.	
	00000	CAUTION	1	00000
8.12 <u>Unloa</u>	d Wafers			
8.12.1	Remove the	monitor wafers and samples fro	om the boat.	
8.13 <u>Meası</u>	ure Monitor W	afers		
8.13.1	Measure the monitor wafe	thickness at 5 sites on each er.	1	-
8.14 <u>Place</u>	System in Sta	ndby	2 3 4	(L (

- 8.14.1 Select the "VACUUM IDLE" recipe.
- 8.14.2 Run the recipe.

NOTE: The cantilever will go in, the system will pump down, and go on hold.

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8.15 Disable Tool in Coral

- 8.15.1 Disable the furnace in Coral.
- 8.15.2 Record the thickness measurements.

9 Solid Source Instructions

9.1 Install the desired boat

9.1.1 Ensure the unwanted quartz boat on the cantilever is sufficiently cool.

NOTE: The programmed cooldown cycle will be finished and the host computer will

show ***** Complete *****



- 9.1.2 **Using the boat fork,** carefully remove the unwanted boat and place it on a quartz plate for storage.
- 9.1.3 **Using the boat fork,** carefully place the desired boat on the cantilever.

9.2 Dehydrate Sources

- 9.2.1 **If the solid sources have been out of the furnace for more than 1 hour,** dehydrate the sources.
 - 9.2.1.1 **Using the boat fork,** place the boat with the solid sources on the cantilever.
 - 9.2.1.2 Ensure each slot adjacent to a solid source wafer has a filler wafer.
 - 9.2.1.3 Process the "DEHYDRATE SOURCES" recipe.
 - 9.2.1.4 When completed, the sources are ready to be used for doping.



10 Process Notes

10.1 Process Summary

10.1.1 **TABLE 4, OXIDATION PROCESS SUMMARY DATA** lists the basic information for the various processes. Contact staff for help selecting a recipe and oxidation time.

	TABLE 4, OXIDATION PROCESS SUMMARY DATA						
Furnace	Recipe	N2 (slm)	O2 (slm)	N2/TLC (slm)	Temp (°C)	Approx. Time (min)	Thick (Å)
CleanOx, Doped Ox	DRY OX (All temps)		4		1000	60	550
					1050	27	400
						31	500
						53	750
						78	1000
	CLEAN OX (All temps)		3.5		850	100	800
					950	32	1000
						57	1500
						80	2000
					1000	30	1500
						41	2000
					4050	55	2500
					1050	30	2200
						48	5000
						300	10000
						600	14000
Doned Ox	ANNEAL (All temps)	5				000	11000
	BORON DOPING	8					
	PHOS DOPING	8					
Oxide Thi • Wet 950C • Wet 10 5000 4000 4000 2000 4000 0 20 40 Oxide Thi	ckness Curves OOC • Wet 1050C • Dry 1050C 60 80 100 dation Time (min)	1600 1400 (¥) 1000 800 400 200	Oxid	de Thick	wet 10500	400 500 (min)	D 600
Note: Oxidation times can	he approximated by this formula					. ,	
				>2			
	New Time = $\frac{(Known T)}{(Known T)}$	Time) * (N	ew Thicki	ness) ²			
	۸)	ποωπ ι πι	ckness)=				



11 Revision History

Rev	Date	Originator	Description of Changes
3	10 Jun 19	T. Olsen	Update document to new format.
2	29 Jun 18	T. Olsen	General update and re-order sub-sections.
1	28 Mar 16	T. Olsen	Initial Release